

|                          |   |                                     |                     |
|--------------------------|---|-------------------------------------|---------------------|
| <b>PCN Number:</b>       | 20161007004                             | <b>PCN Date:</b>                    | October 27, 2016    |
| <b>Title:</b>            | Datasheet for TPA3116D2-Q1/TPA3118D2-Q1 |                                     |                     |
| <b>Customer Contact:</b> | <a href="#">PCN Manager</a>             | <b>Dept:</b>                        | Quality Services    |
| <b>Change Type:</b>      |   |                                     |                     |
| <input type="checkbox"/> | Assembly Site                           | <input type="checkbox"/>            | Design              |
| <input type="checkbox"/> | Assembly Process                        | <input checked="" type="checkbox"/> | Data Sheet          |
| <input type="checkbox"/> | Assembly Materials                      | <input type="checkbox"/>            | Part number change  |
| <input type="checkbox"/> | Mechanical Specification                | <input type="checkbox"/>            | Test Site           |
| <input type="checkbox"/> | Packing/Shipping/Labeling               | <input type="checkbox"/>            | Test Process        |
| <input type="checkbox"/> |   | <input type="checkbox"/>            | Wafer Bump Site     |
| <input type="checkbox"/> |   | <input type="checkbox"/>            | Wafer Bump Material |
| <input type="checkbox"/> |   | <input type="checkbox"/>            | Wafer Bump Process  |
| <input type="checkbox"/> |   | <input type="checkbox"/>            | Wafer Fab Site      |
| <input type="checkbox"/> |   | <input type="checkbox"/>            | Wafer Fab Materials |
| <input type="checkbox"/> |   | <input type="checkbox"/>            | Wafer Fab Process   |

### Notification Details

#### Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below:



#### TPA3116D2-Q1, TPA3118D2-Q1

SLOS862B – JULY 2015 – REVISED OCTOBER 2016

[www.ti.com](http://www.ti.com)

#### Changes from Revision A (August 2015) to Revision B

Page

- Changed [Table 3](#), column R to GND From: Short To: Open and column R to GVDD From: Open To: Short ..... 13
- Changed [Figure 19](#) ..... 19

| Device Family                             | Change From: | Change To:      |
|---|--------------|-----------------|
| <a href="#">TPA3116D2-Q1/TPA3118D2-Q1</a> | SLOS862A     | <b>SLOS862B</b> |

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/lit/ds/symlink/tpa3116d2-q1.pdf>

#### Reason for Change:

To more accurately reflect device characteristics.

#### Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

#### Changes to product identification resulting from this PCN:

None.

#### Product Affected:

|                  |                  |
|------------------|------------------|
| TPA3116D2QDADRQ1 | TPA3118D2QDAPRQ1 |
|------------------|------------------|

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location     | E-Mail   |
|--------------|--|
| USA          | <a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a> |
| Europe       | <a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>     |
| Asia Pacific | <a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>         |
| Japan        | <a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>       |